Title (en)

MODULAR MICROFLUIDIC DEVICES COMPRISING SANDWICHED STENCILS

Title (de)

AUS EINGEKLEMMTEN SCHABLONEN BESTEHENDE, MODULARE, MIKROFLUIDISCHE VORRICHTUNGEN

Title (fr)

DISPOSITIFS MICROFLUIDIQUES MODULAIRES COMPRENANT DES MASQUES PERFORES INTERCALES

Publication

EP 1222141 A1 20020717 (EN)

Application

EP 00968672 A 20001004

Priority

- US 0027366 W 20001004
- US 15756599 P 19991004
- US 45302999 A 19991202

Abstract (en)

[origin: WO0125138A1] The present invention provides modular microfluidic devices and systems, as well as methods for their manufacture. A microfluidic device is provided comprising first and second substrates (59, 60), and at least one stencil (58) sandwiched between the first and second substrates so as to define one or more sealed microstructures therebetween. The stencil is adhered to at least one of the first and second substrates by an adhesive (44). In a preferred embodiment, there is a plurality of sandwiched stencils. Also, the first and second substrates are preferably substantially planar. These microfluidic devices can be rapidly prototyped with low tool-up cost, and can be easily assembled to form three-dimensional structures having complex microfluidic system geometries.

IPC 1-7

B81B 1/00; B01J 19/00; B01L 3/00; G01N 21/05

IPC 8 full level

B01J 19/00 (2006.01); **B01L 3/00** (2006.01); **B32B 38/10** (2006.01); **B81B 1/00** (2006.01); **B81C 3/00** (2006.01); **G01N 21/05** (2006.01); **G01N 27/00** (2006.01); **G01N 27/447** (2006.01); **G01N 35/08** (2006.01); G01N 21/03 (2006.01)

CPC (source: EP)

B01J 19/0093 (2013.01); **B01L 3/502707** (2013.01); **B32B 38/10** (2013.01); **B82Y 30/00** (2013.01); **G01N 21/05** (2013.01); **G01N 27/44791** (2013.01); B01J 2219/0002 (2013.01); B01J 2219/00783 (2013.01); B01J 2219/00819 (2013.01); B01J 2219/00828 (2013.01); B01J 2219/00833 (2013.01); B01J 2219/00835 (2013.01); B01J 2219/00853 (2013.01); B01J 2219/00891 (2013.01); B01J 2219/00912 (2013.01); B01J 2219/00952 (2013.01); B01L 2200/028 (2013.01); B01L 2200/0689 (2013.01); B01L 2300/0864 (2013.01); B01L 2300/0867 (2013.01); B01L 2300/0874 (2013.01); B01L 2300/0887 (2013.01); B01L 2300/165 (2013.01); B01L 2400/0415 (2013.01); B32B 2310/0843 (2013.01); G01N 2021/0346 (2013.01); G01N 2021/058 (2013.01)

Citation (search report)

See references of WO 0125138A1

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)

WO 0125138 A1 20010412; **WO 0125138 A9 20030530**; AU 7854700 A 20010510; EP 1222141 A1 20020717; JP 2003527972 A 20030924

DOCDB simple family (application)

US 0027366 W 20001004; AU 7854700 A 20001004; EP 00968672 A 20001004; JP 2001528097 A 20001004